

EPO-TEK® H35-175MPT

Technical Data Sheet For Reference Only

Electrically Conductive, Silver Epoxy

Date: March 2020

Rev: VII
No. of Components: Single
Mix Ratio by Weight: N/A
Specific Gravity: 3.65
Pot Life: 28 Days

Shelf Life: One year at -40°C

Recommended Cure: 180°C / 1 Hour

Minimum Alternative Cure(s):

May not achieve performance properties listed below

165°C / 1.5 Hours

NOTES:

• Container(s) should be kept closed when not in use.

• Filled systems should be stirred thoroughly before mixing and prior to use.

• Performance properties (rheology, conductivity, others) of the product may vary from those stated on the data sheet when bi-pak/syringe packaging or post-processing of any kind is performed. Epoxy's warranties shall not apply to any products that have been reprocessed or repackaged from Epoxy's delivered status/container into any other containers of any kind, including but not limited to syringes, bi-paks, cartridges, pouches, tubes, capsules, films or other packages.

• Complies with the requirements of MIL-STD 883/Method 5011.

Product Description: EPO-TEK® H35-175MPT is a single component, silver-filled epoxy for hybrid die and component attach.

<u>Typical Properties:</u> Cure condition: 180°C / 1 Hour Different batches, conditions & applications yield differing results.

Data below is not guaranteed. To be used as a guide only, not as a specification. * denotes test on lot acceptance basis

PHYSICAL PROPERTIES:			
	0:1		
* Color (before cure):	Silver		
* Consistency:		h thixotropic pas	
* Viscosity (23°C) @ 2.5 rpm:	90	0,000-110,000	cPs
Thixotropic Index:		4.6	
* Glass Transition Temp:	≥ 100		°C (Dynamic Cure: 20-300°C/ISO 25 Min; Ramp -10-200°C @20°C/Min)
Coefficient of Thermal Expansion (CTE):		
_ :	ow Ta:	35	x 10 ⁻⁶ in/in°C
	ve Ta:	123	x 10 ⁻⁶ in/in°C
Shore D Hardness:	•• · · g.	83	X 10 Highli G
Lap Shear @ 23°C:		1,693	psi
* Die Shear @ 23°C:		≥ 10	•
			Kg 3,556 psi °C
Degradation Temp:		354	
Weight Loss:			0/
_	200°C:	0.03	%
	250°C:	0.05	%
@ 3	300°C:	0.13	%
Suggested Operating Temperature: < 30		< 300	°C (Intermittent)
Storage Modulus:		423,781	psi
* Ion Content:	Cl⁻:	< 200 ppm	Na ⁺ : < 50 ppm
	NH ₄ +:	32 ppm	K ⁺ : < 50 ppm
* Particle Size:		≤ 20	microns

ELECTRICAL AND THERMAL PROPERTIES:			
Thermal Conductivity:	2.7	7 W/mK	
* Volume Resistivity @ 23°C:	≤ 0.0005	5 Ohm-cm	
Dielectric Constant (1KHz):	N/A	4	
Dissipation Factor (1KHz):	N/A	4	



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EPO-TEK® H35-175MPT Advantages & Suggested Application Notes:

- This epoxy can be classified as a higher viscosity version of EPO-TEK® H35-175MP, suggested for the following purposes:
 - Used for improved stencil printing via small apertures (not for dispensing).
 - Less flow-out between small pads like 0402 or 0603 caps and resistors.
- Performs exceptionally well as a die attach for small chips such as GaAs, LEDs and diodes.
- Capable of resisting 260°C green reflow process, low outgassing in hermetic lid-seal processes near 300°C, and organic burn-in up to 150°C/1000 hours storage.
- Certified to MIL-STD 883/Test Method 5011 –yields low levels of water extractable monovalent ions such as Chlorides.
- Capable of JEDEC Level II die-attach packaging on die-paddles and lead-frames.
- Widely used epoxy; popular choice for silver-filled epoxies; opto-packaging, hybrids, and many types of substrates including kovar, ceramic and BT